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Global IC Package Substrate Material Market 2025 by Company, Regions, Type and Application, Forecast to 2031

https://marketpublishers.com/r/G36A0A4EF885EN.html
Date: September 2025
Pages: 108
Price: US$ 3,132.00 (Single User License)
ID: G36A0A4EF885EN

Abstracts

According to our (Global Info Research) latest study, the global IC Package Substrate Material market size was valued at US$ 7151 million in 2024 and is forecast to a readjusted size of USD 11900 million by 2031 with a CAGR of 7.5% during review period.

IC package substrate materials play a crucial role in providing a reliable and efficient electrical connection between the integrated circuit (IC) chip and the rest of the electronic system. The choice of substrate material depends on various factors such as the application, performance requirements, and thermal considerations.

At the regional level, the Chinese mainland market accounts for about 9% of the world. From the product perspective, substrate resin is currently the most important packaging material, accounting for 41%, and it is expected that it will continue to be the largest type in the future. From the application perspective, FC-BGA is currently the most important application, accounting for 38%.

At present, global manufacturers are mainly concentrated in the Asia-Pacific region, and China has also developed very rapidly in recent years. Major companies include Ajinomoto, Changchun, Mitsubishi Gas, Nanya Plastics, Showa Denko, Mitsui Metals and Panasonic Electric, etc. The top five companies account for more than 30%. It is expected that industry competition will become more intense in the next few years, especially in the Chinese market.

IC packaging substrate materials are affected by the following factors: First, the 2019 COVID-19 pandemic swept the world, causing serious impacts on all industries around

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the world. Although high-tech industries such as semiconductor chips have not been fatally hit, the fluctuations in the macro environment have also indirectly affected the normal development of the semiconductor packaging industry market. Second, with the expansion of Sino-US trade frictions, many Taiwanese and Chinese companies have been affected, and some Chinese semiconductor manufacturers have chosen to build factories in other countries and regions for production. Third, because chips belong to high-tech industries, they require a high level of manufacturing technology. Some countries or companies have mastered the latest technology, but due to some factors, they have not been made public. The existence of technical barriers has restricted the development of the IC packaging substrate material industry. Of course, challenges and opportunities coexist. In recent years, the United States, Europe, Japan and other countries have introduced bills to increase support for their IC packaging substrate materials and related industries, including various grants and subsidy policies. The rise of industries such as 5G/6G, the Internet of Things, and new energy vehicles has increased the demand for chips and greatly promoted the development of the chip industry. In addition, the rapid development of integrated circuits has driven the large-scale expansion of the entire semiconductor industry. Personal computers and smartphones are still important sources of demand for the chip industry, and strong demand is an important factor in the expansion of the chip industry. With the improvement of living standards, people's entertainment needs have been improved. The rise of wearable devices and entertainment devices has further increased the demand for chips. Chip packaging technology has involved various materials, electronics, thermal, mechanics, chemistry, reliability and other disciplines. It is a high-tech industry that is increasingly valued and developed in parallel with integrated circuit chips. With the simultaneous development of design, chip manufacturing and packaging and testing, the importance of packaging in the entire IC industry chain is unquestionable. The proportions are gradually tending towards reasonable and coordinated development, and its importance is increasing.

This report is a detailed and comprehensive analysis for global IC Package Substrate Material market. Both quantitative and qualitative analyses are presented by company, by region & country, by Type and by Application. As the market is constantly changing, this report explores the competition, supply and demand trends, as well as key factors that contribute to its changing demands across many markets. Company profiles and product examples of selected competitors, along with market share estimates of some of the selected leaders for the year 2025, are provided.

Key Features:

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Global IC Package Substrate Material market size and forecasts, in consumption value ($ Million), 2020-2031

Global IC Package Substrate Material market size and forecasts by region and country, in consumption value ($ Million), 2020-2031

Global IC Package Substrate Material market size and forecasts, by Type and by Application, in consumption value ($ Million), 2020-2031

Global IC Package Substrate Material market shares of main players, in revenue ($ Million), 2020-2025

The Primary Objectives in This Report Are:

To determine the size of the total market opportunity of global and key countries
To assess the growth potential for IC Package Substrate Material
To forecast future growth in each product and end-use market
To assess competitive factors affecting the marketplace

This report profiles key players in the global IC Package Substrate Material market based on the following parameters - company overview, revenue, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include Mitsubishi Gas Chemical, Ajinomoto, Resonac Corporation, Panasonic, Mitsui Mining & Smelting, Nan Ya Plastics, Sumitomo Bakelite, Chang Chun Group, Sekisui Chemical, WaferChem Technology, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Market segmentation

IC Package Substrate Material market is split by Type and by Application. For the period 2020-2031, the growth among segments provides accurate calculations and forecasts for Consumption Value by Type and by Application. This analysis can help you expand your business by targeting qualified niche markets.

Market segment by Type

Substrate Resin

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Copper Foil

Insulation Materials

Drill

Other

Market segment by Application

FC-BGA

FC-CSP

WB BGA

WB CSP

RF Module

Other

Market segment by players, this report covers

Mitsubishi Gas Chemical

Ajinomoto

Resonac Corporation

Panasonic

Mitsui Mining & Smelting

Nan Ya Plastics

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Sumitomo Bakelite

Chang Chun Group

Sekisui Chemical

WaferChem Technology

ITEQ

Market segment by regions, regional analysis covers

North America (United States, Canada and Mexico)
Europe (Germany, France, UK, Russia, Italy and Rest of Europe)
Asia-Pacific (China, Japan, South Korea, India, Southeast Asia and Rest of Asia-Pacific)
South America (Brazil, Rest of South America)
Middle East & Africa (Turkey, Saudi Arabia, UAE, Rest of Middle East & Africa)

The content of the study subjects, includes a total of 13 chapters:

Chapter 1, to describe IC Package Substrate Material product scope, market overview, market estimation caveats and base year.

Chapter 2, to profile the top players of IC Package Substrate Material, with revenue, gross margin, and global market share of IC Package Substrate Material from 2020 to 2025.

Chapter 3, the IC Package Substrate Material competitive situation, revenue, and global market share of top players are analyzed emphatically by landscape contrast.

Chapter 4 and 5, to segment the market size by Type and by Application, with consumption value and growth rate by Type, by Application, from 2020 to 2031

Chapter 6, 7, 8, 9, and 10, to break the market size data at the country level, with revenue and market share for key countries in the world, from 2020 to 2025.and IC Package Substrate Material market forecast, by regions, by Type and by Application, with consumption value, from 2026 to 2031.

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Chapter 11, market dynamics, drivers, restraints, trends, Porters Five Forces analysis.

Chapter 12, the key raw materials and key suppliers, and industry chain of IC Package Substrate Material.

Chapter 13, to describe IC Package Substrate Material research findings and conclusion.

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